

PCN: V19-002-48475413-0A

Product Change Notice

Issue Date: 20 September 2019

Change Type:

Product Moisture Sensitivity Level (MSL) reclassification for ChipLED part numbers listed below.

Parts Affected:

HSMF-C116 HSMF-P11A HSMF-C127

Description and Extent of Change:

Encapsulant material change. Product with new encapsulant material will be reclassified as MSL 4.

Reasons for Change:

The encapsulant material production was obsoleted.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

There is no change in fit, form and function. Changes in product handling will be reflected in its packaging and new datasheet.

Current Packaging	New Packaging
CAUTION LEVEL This bag contains 2a MOISTURE-SENSITIVE DEVICES 2a 1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH).	CAUTION LEVEL This bag contains 4 MOISTURE-SENSITIVE DEVICES 4 1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH).
2. Peak package body temperature : 260°C	2. Peak package body temperature : 260°C
 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must a) Mounted within : 672 hours of factory conditions ≤ 30°C/60% b) stored at < 10% RH. 	 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must a) Mounted within : 72 hours of factory conditions < 30°C /60% b) stored at < 10% RH.
 4. Devices require bake, before mounting, if: a) Humidity Indicator Card is > 10% when read at 23 ±5°C b) 3a or 3b not met. 	 4. Devices require bake, before mounting, if: a) Humidity Indicator Card is > 10% when read at 23 ±5 ℃ b) 3a or 3b not met.
5. If baking is required, devices may be baked for 20 hours at 60 \pm 5°C	5. If baking is required, devices may be baked for 20 hours at 60 $\pm5^\circ\!\mathrm{C}$
Note: If device containers cannot be subjected to high temperature or shorter bake times are desired. reference IPC/JEDEC J-STD-033 for bake procedure	Note: If device containers cannot be subjected to high temperature or shorter bake times are desired. reference IPC/JEDEC J-STD-033 for bake procedure
Bag Seal Date: If Blank, see adjacent bar code label Note: Level and body temperature defined by IPC/JEDEC J-STD-020	Bag Seal Date: If Blank, see adjacent bar code label Note: Level and body temperature defined by IPC/JEDEC J-STD-020





Effective Date of Change:

Shipment will contain parts with new MSL rating starting 20th March 2020.

Qualification Data:

Reliability data will be provided upon request.

These changes have been reviewed and approved by Broadcom Limited engineers and managers per Broadcom Limited procedure: Change Control and Customer Notification, A-5962-6052-80.

Please contact your Broadcom Limited field sales engineer or Contact Center (<u>http://www.broadcom.com</u>) for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.